SECURITIES AND EXCHANGE COMMISSION

WASHINGTON, D.C. 20549

FORM 8-K

CURRENT REPORT

Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): January 14, 2019

DIODES INCORPORATED

(Exact name of Registrant as Specified in Its Charter)

Delaware (State or Other Jurisdiction of Incorporation) 002-25577 (Commission File Number) 95-2039518 (IRS Employer Identification No.)

4949 Hedgcoxe Road, Suite 200, Plano, TX (Address of Principal Executive Offices)

75024 (Zip Code)

Registrant's Telephone Number, Including Area Code: (972) 987-3900

Not Applicable (Former Name or Former Address, if Changed Since Last Report)

	the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions (see ral Instructions A.2. below):
	Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
	Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
	Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
	Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c)) ate by check mark whether the registrant is an emerging growth company as defined in Rule 405 of the Securities Act of 1933 (§230.405 of this chapter) or Rule 12b-2 of courities Exchange Act of 1934 (§240.12b-2 of this chapter).
Emerg	ging growth company \square
	emerging growth company, indicate by check mark if the registrant has elected not to use the extended transition period for complying with any new or revised financial nting standards provided pursuant to Section 13(a) of the Exchange Act.

Item 8.01 Other Events.

From time to time, Diodes Incorporated (the "Company") may give corporate presentations to its customers, suppliers and other related interested parties. Copies of the

Item 9.01 Financial Statements and Exhibits.

(d) Exhibits.

Exhibit Number Description

99.1 Corporate Presentation Slides

Index to Exhibits

Exhibit Number

Description

99.1 <u>Corporate Presentation Slides</u>

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the Registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized

Dated: January 14, 2019 DIODES INCORPORATED

Company's corporate presentation slides, updated on January 14, 2019, are attached herewith as Exhibit 99.1.

By /s/ Richard D. White

RICHARD D. WHITE Chief Financial Officer



Needham 21st Annual Growth Conference

New York, New York January 15th, 2019 Any statements set forth herein that are not historical facts are forward-looking statements that involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. Such forward-looking statements include, but are not limited to, statements regarding updates to Diodes Incorporated's fourth quarter 2018 business outlook as of November 6, 2018, which include the following: expect revenue to be approximately \$315 million, plus or minus 3 percent, or down 1.9 percent sequentially; expect GAAP gross margin to be 36.0 percent, plus or minus 1 percent; non-GAAP operating expenses, which are GAAP operating expenses adjusted for amortization of acquisition-related intangible assets, are expected to be approximately 21.0 percent of revenue, plus or minus 1 percent; expect net interest expense to be approximately \$2.0 million; expect tax rate to be 29.5 percent, plus or minus 3 percent; shares used to calculate diluted EPS for the second quarter are anticipated to be approximately 52.2 million; purchase accounting adjustments for Pericom and previous acquisitions of \$3.5 million after tax are not included in these non-GAAP estimates; and other statements identified by words such as "estimates," "expects," "projects," "plans," "will," and similar expressions.

Potential risks and uncertainties include, but are not limited to, such factors as: the risk that such expectations may not be met; the risk that the expected benefits of acquisitions may not be realized or that integration of acquired businesses may not continue as rapidly as we anticipate; the risk that we may not be able to maintain our current performance, costs, and loadings in our manufacturing facilities; the risk that we may not be able to increase our automotive, industrial, or other revenue and market share; risks of domestic and foreign operations, including excessive operation costs, labor shortages, higher tax rates, and our joint venture prospects; the risk that we may not continue our share repurchase program; the risks of cyclical downturns in the semiconductor industry and of changes in end-market demand or product mix that may affect gross margin or render inventory obsolete; the risk of unfavorable currency exchange rates; the risk that our future outlook or guidance may be incorrect; the risks of global economic weakness or instability in global financial markets; the risks of trade restrictions, tariffs, or embargoes; the risk of breaches of our information technology systems; and other information, including the "Risk Factors" detailed from time to time in Diodes' filings with the United States Securities and Exchange Commission.

This presentation also contains non-GAAP measures. See the Company's press release on November 6, 2018 titled, "Diodes Incorporated Reports Third Quarter 2018 Financial Results" for detailed information related to the Company's non-GAAP measures and a reconciliation of GAAP net income to non-GAAP net income.



Dr. Keh-Shew Lu

President and CEO

Diodes Incorporated Since 2005
Texas Instruments 27 years

Experience:

- Senior Vice President of TI Worldwide Analog and Logic
- President of Texas Instruments Asia

Education:

- Master's Degree and Doctorate in Electrical Engineering Texas Tech University
- Bachelor's Degree in Engineering National Cheng Kung University - Taiwan





Laura Mehrl (冯蓉媞)

Company spokesperson, Director of Investor Relations Since May 2010

Experience:

- Director of Investor Relations, Diodes Incorporated, Plano, Texas
- Senior Business Development Manager, STMicroelectronics, Carrollton, Texas
- Sales Director for Analog Devices Inc., Shanghai, China
- Product Marketing Manager at Texas Instruments (TI), Dallas, Texas
- Senior Engineer at Lattice Semiconductor Inc., Hillsboro, Oregon
- Wafer fab design engineer and product engineer at TI, Lubbock, Texas

Education:

- MBA with concentration in International Marketing, Texas Tech University
- BS in Electrical and Computer Engineering, University of Iowa



A leading global manufacturer and supplier of high-quality application specific, standard products within the broad discrete, logic, analog and mixed-signal markets, serving the Automotive, Industrial, Consumer, Communications, and Computing segments.





Global Operations and World-class Manufacturing & Packaging

- NASDAQ: DIOD
- Founded in 1959
- Headquartered in Plano, TX; 21 locations globally
- Manufacturing in UK, Germany, China, and Taiwan
- ISO9001:2008 Certified / TS16949:2009 Certified
 ISO14001 Certified
- Key acquisitions:
 - Anachip Corporation, Taiwan Jan. 2006
 - Advanced Power Devices Nov. 2006
 - Zetex June 2008
 - Power Analog Microelectronics (PAM) Oct. 2012
 - BCD Semiconductor Mar. 2013
 - Pericom Semiconductor Nov. 2015
- Over 7700 employees worldwide
- 27 consecutive years of profitability









2018: Record Annual Revenue & Gross Profit



*2018 estimate based on midpoint of 40'18 guidance as provided on November 6, 2018





Mission:

Profitability growth to expand shareholder value

Strategy:

Grow revenue to \$2.5B at 40% GPM

Goal:

\$1B Gross Profit by 2025





	2017		2025	Implied CAGR
NR	\$1B	\rightarrow	2.5B	11.4%
GP%	35%	\rightarrow	40%	
GP\$	\$360M	\rightarrow	\$1B	13.6%
R&D%	5%	\rightarrow	7%	
SG&A%	15%	\rightarrow	13%	
Op. Profit	15%	→	20%	

Based on the midpoint of 4Q18 guidance, NR would grow 15.2% YoY, GP\$ would grow 20% YoY in 2018



~40% of revenue

Automotive

Connected driving, comfort/style/safety, electrification/powertrain

Industrial

- Embedded systems and precision controls

~60% of revenue

Consumer

loT: wearables, home automation, smart infrastructure

Communications

- Smart phones: advanced protocols and charging

Computing

- Cloud computing: server, storage, data centers



Connected driving

- ADAS (Advanced Driver Assistance Systems)
- **Telematics**



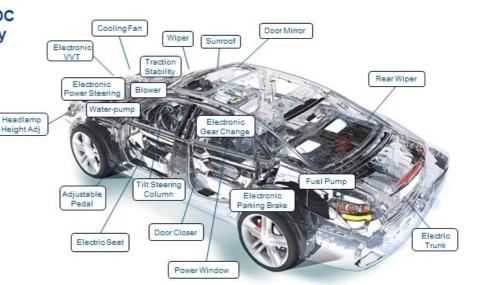


Migrating from Brushed to BLDC Motors (~ 30 per vehicle)

Automotive market moving to BLDC motors for reliability and efficiency

 Forecast to grow to 3.8 Billion units by 2021

Diodes Key Products	\$/Car
MOSFETs	\$18.75
Diodes Rectifiers	\$2.60
Hall Sensors	\$0.50
Gate Drivers	\$1.50
Crystals/XO	\$2.00
Total	\$25.35



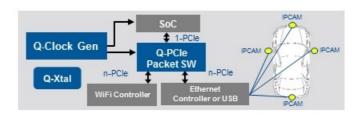


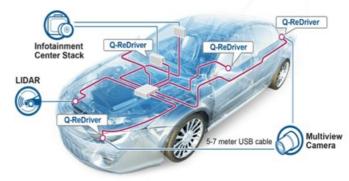
Higher speed data rates and increased number of channels

Robust and reliable data transfer

- ADAS, Telematics and Infotainment systems are merging into Connected Driving
- Forecast to grow to 280 Million units by 2021

Diodes Key Products	\$/Car
Connectivity: (PCle SW + ReDrivers, Signal SW, USB charger)	\$8.50
Crystal/XO and Clocks	\$3.50
Automotive Analog IC	\$1.52
MOSFETs, BJT	\$6.62
Diodes and Rectifiers	\$3.60
Total	\$23.74







Diodes can address \$70 of semiconductor content per vehicle

Diodes Key Products	\$/Car		
Analog	\$2.02		
Power Management	\$5.99		
MOS/BJT	\$35.02		
Diodes and Rectifiers	\$12.69		
Timing and Connectivity	\$15.03		
Total	\$70.75		

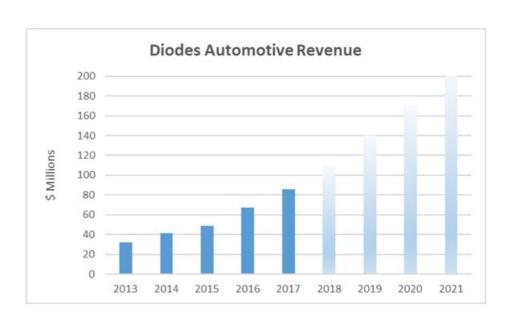


^{*} SemiCast Automotive Report 2016 forecast





- Automotive revenue 27%
 CAGR 2013 to 2017
- Automotive represented 9% of Diodes' total revenue in 2018
- Automotive will continue to be an increasingly significant market segment for Diodes





- Increasing IC content in embedded systems
- Switching and signal path for networked systems and automation
- Signal conditioning and timing for precision controls
- Motor controls, sensors and power management for smart meters





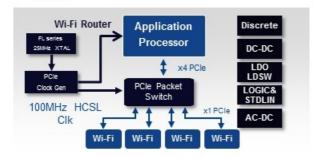
- M2M Dominated by short range technology
 - 73% of them are short range, mostly Wi-Fi
- 2017: connections @ 750 million
- 2023: connections @ 2600 million

M2M - By product

- IoT and M2M Modems
- Routers
- POS
- Wireless beacons
- Others

M2M - By application

- Smart Infrastructure
- POS
- Manufacturing / Industrial



CispleyPort DVI Scaler DP PCP/ Switch/ Redriver Santon/ Switch DVI Scaler DP DC Bus CPU SATA Switch/ Redriver SATA Switch/ Redriver W/ Buffer W/ Buffer DVISB 2.0 USB 3.0 USB

POS

Diodes Key Products	\$ / Device
Analog	\$0.20
Power Management	\$1.30
MOS/BJT	\$3.39
Diodes and Rectifiers	\$2.99
Timing and Connectivity	\$3.50

\$11.38

Growth Opportunities:

- Power
- Xtal and clock
- Packet switch

Total

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Smart Infrastructure

Consumer & Home





Asset Tracking



Wearables







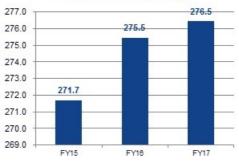




Retail Enterprise

Security & Surveillance

Consumer (\$M)



Diodes Key Products	\$ / Box		
Analog	>\$0.20		
Power Management	>\$1.30		
MOS/BJT	>\$10.00		
Diodes and Rectifiers	>\$5.00		
Timing and Connectivity	\$3.50		
Total	\$20.00		



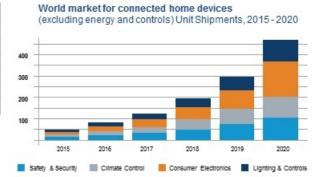
Smart Home - up to 477Mu

- Safety and Security
- Climate Control
- Consumer Electronics
- Lighting control

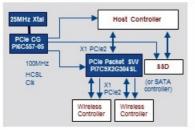
Growth Opportunities

- Power
- LED driver
- Xtal and clock
- Packet switch

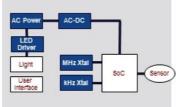
Diodes Key Products	\$ / Box
Analog	\$0.25 ~ \$0.40
Power Management	\$1.80
MOS/BJT	\$1.10
Diodes and Rectifiers	\$0.50
Timing and Connectivity	\$3.50
Total	\$7.30







Smart Lighting



Smart Speaker



Digital Assistant





- Focus on signal integrity and higher data rates
- Proliferation of USB Type-CTM connectivity and power delivery
- Power regulation and protection for new features
- Advanced power solutions for quick charge protocols





Smartphone - Flat year in 2017

What's next? Understand the impact

- Smart speaker/loT rising
- = AR/VR
- Foldable screens
- = 5G
- Smartwatches

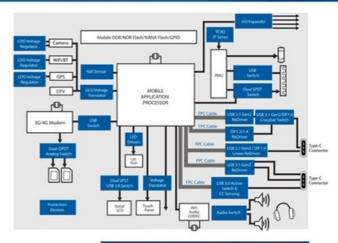
Growth Opportunities

- Type-C
- MUX
- MOSFET
- LDO, OVP LDSW, Audio, DCDC, LED/OLED Driver, ACDC

Top Five Smartphone Companies in SEA, Calendar Year 2017

Company	2016 Shipment Volumes	2016 Market Share	2017 Shipment Volumes	2017 Market Share	Year-Over-Year Change
1. Samsung	23.3	23.0%	29.3	29.1%	25.8%
2. OPPO	13.3	13.2%	17.2	17.0%	29.3%
3. Vivo	3.3	3.2%	7.2	7.2%	118.2%
4. Huawei	5.2	5.1%	5.4	5.4%	3.8%
5. Apple	4.6	4.5%	4.5	4.4%	-2.2%
Others	51.6	51.0%	37.1	36.8%	-29.1%
Total	101.3	100.0%	100.7	100.0%	-0.6%

Source IDC Worldwide Quarterly Mobile Phone Tracker, March 2018





Diodes Key Products	\$ / Phone
Analog	\$0.55
Power Management	\$1.50
MOS/BJT	\$0.33
Diodes and Rectifiers	\$0.42
Timing and Connectivity	\$3.00
Total	\$5.80



- WW enterprise and service provider router market grew 4% in 2017 to \$12.5B
- Continues to exhibit healthy growth, driven by network refreshes and investments in the fast-growing campus and datacenter segments

Growth Opportunities

- Power
- Xtal XO, and clock
- Packet switch
- ReDriver



Switching & Router Market Leaders



Diodes Key Products	\$ / Router		
Analog	\$0.20		
Power Management	\$0.30		
MOS/BJT	\$3.70		
Diodes and Rectifiers	\$2.10		
Timing and Connectivity	\$13.00		
Total	\$19.30		



- ReDriver support for USB connectivity
- Wide range of signal protocols: PCle, SAS, SATA, GbE, USB
- MUX products for high capacity solid state storage
- Crystal oscillators for increasing clocking speeds

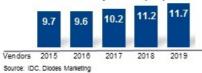




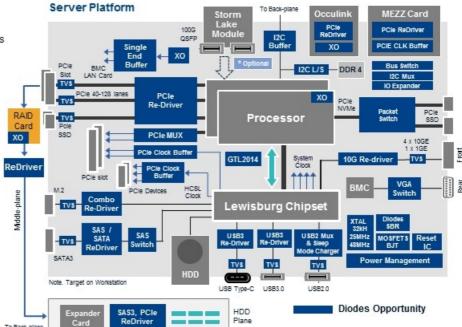
Server Platform Solution

- Total unit shipment Growth (CAGR) = 3.82%
- Almost all of Server vendors are our existing customers
- ODM direct has the highest volume mainly in TW
- Diodes products are well positioned in this segment
 - Connectivity, Signal Integrity, Timing, Standard Linear, Power Management, Power Switches and Protection devices

WW Server total shipments (Mu)



Diodes Key Products	\$ / Server	
Connectivity, Signal Integrity and Timing	\$7.00	
Analog	\$0.50	
Power Management	\$3.30	
MOS/BJT	\$6.70	
Diodes, Rectifiers and TVS	\$3.50	
Total	\$21.00	

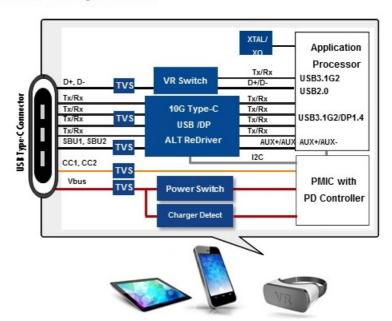




Data speed, flexibility, and simplicity of use are key drivers

- Supports data, video, and power
- USB-C adoption to grow from 300M (2016) to 4B units (2021)

Diodes Key Products	\$ / Device
Connectivity, Signal Integrity and Timing	\$2.05
Analog (DCDC, LDO, Sleep Mode Charger etc)	\$0.64
Power Management Switch	\$0.46
TVS	\$0.50
Total	\$2.55 ~ \$3.65

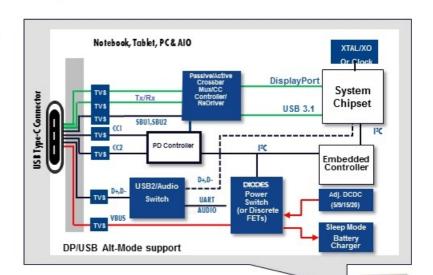




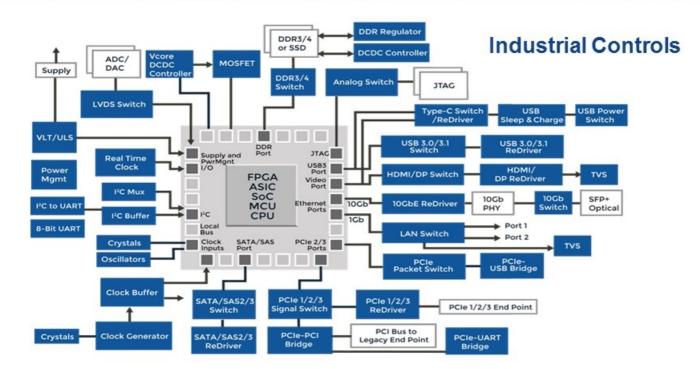
High level of integration and speed are key drivers

- Enables single interface to peripherals for data, video and charging
- Multiple USB-C ports per system

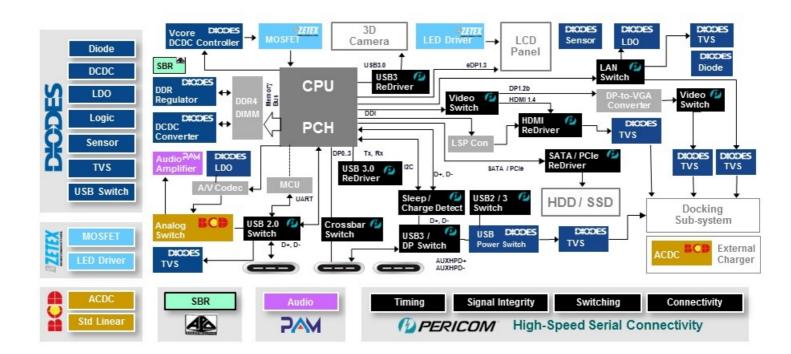
Diodes Key Products	\$ / System
Connectivity, Signal Integrity and Timing	\$3.25
Analog (DCDC, LDO, Sleep Mode Charger etc)	\$0.89
Power Management Switch	\$0.40
MOSFET/BJT	\$0.25
Diodes, Rectifiers and TVS	\$0.50
Total (per USB-C port)	\$5.29











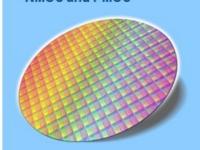


Products Doos 20Ghps ReDrivers and

- 20Gbps ReDrivers and Switches
- Automotive Packet Switch for Telematics / ADAS
- Complete USB Type-C™ Signal Switching
- High speed clocking for cloud computing
- Ultra low power and low noise LDOs for IoT
- Low Cj TVS for signal integrity
- Lowest rps(on) LDMOS for battery efficiency

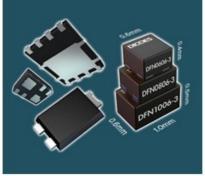
Wafer Fab

- High performance 8" MOSFET trench technology
- Advanced Epi bipolar transistor processes
- Proprietary rectifier technology
- Rugged automotive grade NMOS and PMOS



Assembly/Test

- Compact QFN and DFN
- Power density PowerDI
- Chip scale packaging and plating capability
- Extensive multi-chip package technology





Focus: Miniaturization and Power Efficiency



~ 2018

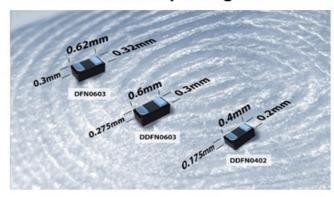
2019~



Miniaturization and Multi-Chip Packaging

Miniaturization DDFN0402

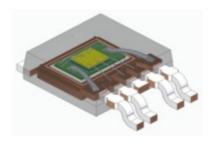
the smallest discrete semiconductor package



Multi-Chip Packaging

Dual-Flat No-Lead (DFN) DDFN (Encapsulated CSP) Chip-Scale Package (CSP)

HS IntelliFET: ZXMS3001







Packaging

- Shanghai-based packaging with capacity over 34 billion units
- Chengdu facility has potential capacity 3X of Shanghai
- Additional facilities in Neuhaus, Germany and Chengdu, China



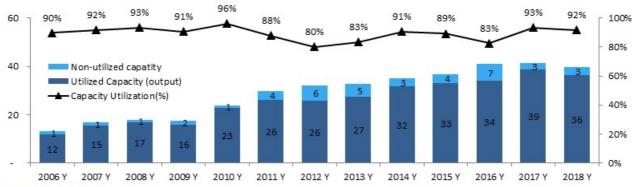
Wafer Fabs

- Two fabs in Shanghai (6" and 8"), one discrete fab in Oldham, UK (6")
- Bipolar, BiCMOS, CMOS and BCD process
- Strong engineering capabilities



Economies of Scale: Capacity & Loading Percentage in SAT & CAT

*CapEx Model = 5% - 9% of Revenue



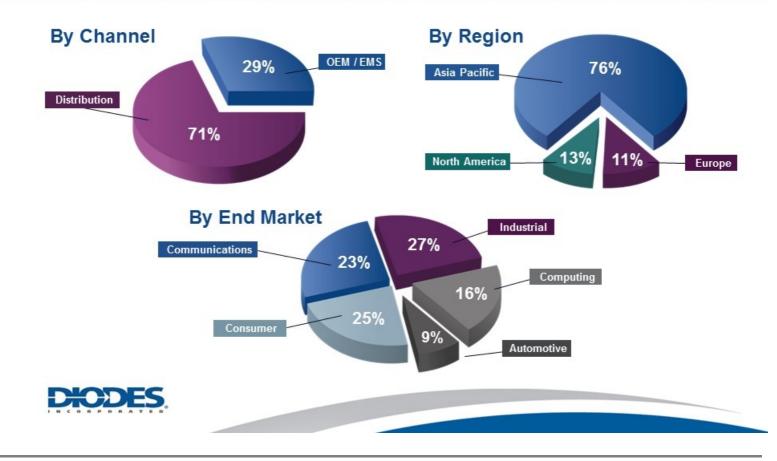


In millions, except per share	3Q17	2Q18	3Q18	YoY
Revenue	\$285.2	\$304.1	\$320.9	12.5%
Gross Profit (GAAP)	\$96.3	\$107.3	\$115.2	19.6%
Gross Profit Margin % (GAAP)	33.8%	35.3%	35.9%	+210bp
Net Income (GAAP)	\$14.5	\$25.1	\$30.9	
Net Income (non-GAAP)	\$22.6	\$29.3	\$34.5	52.7%
EPS (non-GAAP)	\$0.45	\$0.58	\$0.68	51%
Cash Flow from Operations	\$40.9	\$34.4	\$35.5	
EBITDA (non-GAAP)	\$46.8	\$64.5	\$72.0	53.9%



In millions	Dec 31, 2016	Dec 31, 2017	Sept 30, 2018
Cash	\$248	\$204	\$150
Short-term Investments	\$30	\$5	\$7
Inventory	\$193	\$217	\$219
Current Assets	\$733	\$662	\$647
Total Assets	\$1529	\$1489	\$1467
Long-term Debt (including the current portion)	\$413	\$247	\$166
Total Liabilities	\$708	\$615	\$515
Total Equity	\$820	\$874	\$952





- Revenue to be approximately \$315 million, plus or minus 3 percent, or down 1.9% q/q
- GAAP gross margin to be 36.0%, plus or minus 1%
- Non-GAAP operating expenses, which are GAAP operating expenses adjusted for amortization of acquisition-related intangible assets, are expected to be approximately 21.0% of revenue, +/- 1%
- Interest expense to be approximately \$2.0 million, and income tax rate is expected to be 29.5%, +/- 3%
- Shares used to calculate diluted EPS approximately 52.2 million
- Purchase accounting adjustments of \$3.5 million, after tax, for Pericom and previous acquisition are not included in these non-GAAP estimates

*Guidance as provided on November 6, 2018



Summary Page 39

- Vision: Expand shareholder value
- Mission: Profitability growth to drive 20% operating profit
- Next Strategic Goal: \$1B gross profit
- Tactics:
 - Increased focus on high-margin Automotive, Industrial and Pericom products
 - Investment for technology leadership in target products, fab processes, and advanced packaging
 - System solutions to drive business expansion



